

INTERNATIONAL CONFERENCE ON

SOLID STATE DEVICES AND MATERIALS

Sep. 7-10, 2027 Grand Cube Osaka



Grand Cube Osaka

Scope of Conference

1. Advanced CMOS: Material Science / Process Engineering / Device Technology
2. Advanced and Emerging Memories / New Applications
3. Heterogeneous and 3D Integration / Interconnect / MEMS
4. Power / High-speed Devices and Materials
5. Photonics: Devices / Integration / Related Technology
6. Energy Harvesting and Converting Devices and Materials
7. Organic / Molecular / Bio-electronics
8. Low Dimensional Devices and Materials
9. Novel Functional / Quantum / Spintronic Devices and Materials
10. Thin Film Electronics: Oxide / Non-single Crystalline / Novel Process
11. Advanced Materials: Synthesis / Crystal Growth / Characterization
12. Advanced and Innovative Circuits / Systems Interacting with Devices and Materials



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The banquet will be held at **UNIVERSAL STUDIOS JAPAN**.

Conference Chairs

Organizing : Tsunenobu Kimoto (Kyoto Univ.)

Program : Toshifumi Irisawa (AIST)

Steering : Heiji Watanabe (The Univ. of Osaka)

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